Package Outline Drawing

W4x5.20K

20 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP)

Rev 0, 8/14

2. Dimension is measured at the maximum bump diameter parallel to primary datum [Z].
3. Primary datum [Z] and seating plane are defined by the spherical crowns of the bump.
4. Bump position designation per JESD 95-1, SPP-010.
5. There shall be a minimum clearance of 0.10mm between the edge of the bump and the body edge.